

STB14NF10
STP14NF10 STP14NF10FP
N-CHANNEL 100V - 0.115 Ω - 15A TO-220/TO-220FP/D²PAK
LOW GATE CHARGE STripFET™ II POWER MOSFET

TYPE	V _{DSS}	R _{D(on)}	I _D
STB14NF10	100 V	<0.13 Ω	15 A
STP14NF10	100 V	<0.13 Ω	15 A
STP14NF10FP	100 V	<0.13 Ω	10 A

- TYPICAL R_{D(on)} = 0.115 Ω
- EXCEPTIONAL dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- APPLICATION ORIENTED CHARACTERIZATION
- SURFACE-MOUNTING D²PAK (TO-263) POWER PACKAGE IN TUBE (NO SUFFIX) OR IN TAPE & REEL (SUFFIX "T4")

DESCRIPTION

This MOSFET series realized with STMicroelectronics unique STripFET™ process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency, high-frequency isolated DC-DC converters for Telecom and Computer applications. It is also intended for any applications with low gate drive requirements.

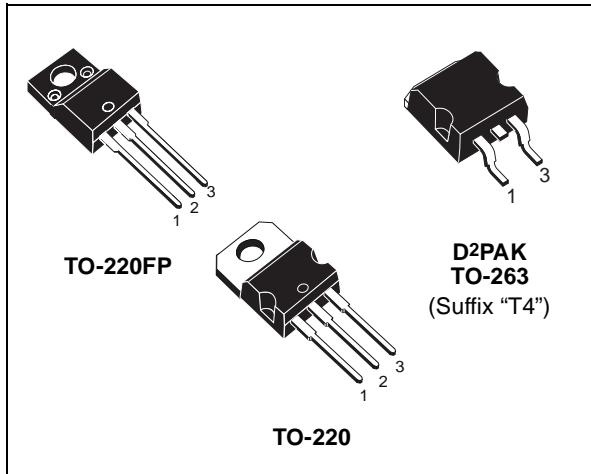
APPLICATIONS

- HIGH-EFFICIENCY DC-DC CONVERTERS
- UPS AND MOTOR CONTROL

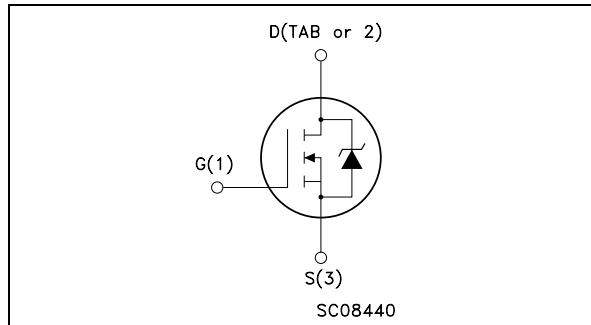
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STB14NF10	STP14NF10FP	
V _{DS}	Drain-source Voltage (V _{GS} = 0)	100		V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 kΩ)	100		V
V _{GS}	Gate- source Voltage	± 20		V
I _D	Drain Current (continuous) at T _C = 25°C	15	10	A
I _D	Drain Current (continuous) at T _C = 100°C	10	6.3	A
I _{DM(•)}	Drain Current (pulsed)	60	40	A
P _{tot}	Total Dissipation at T _C = 25°C	60	25	W
	Derating Factor	0.4	0.17	W/°C
dv/dt (1)	Peak Diode Recovery voltage slope	9		V/ns
EAS (2)	Single Pulse Avalanche Energy	70		mJ
V _{ISO}	Insulation Withstand Voltage (DC)	-----	2000	V
T _{stg}	Storage Temperature	-55 to 175		°C
T _j	Operating Junction Temperature			

(•) Pulse width limited by safe operating area.



INTERNAL SCHEMATIC DIAGRAM



(1) I_{SD} ≤ 14A, di/dt ≤ 300A/μs, V_{DD} ≤ V_{(BR)DSS}, T_j ≤ T_{JMAX}

(2) Starting T_j = 25 °C, I_D = 15A, V_{DD}= 50V

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THERMAL DATA

		D ² PAK TO-220	TO-220FP	
Rthj-case	Thermal Resistance Junction-case	Max	2.5	6 °C/W
Rthj-amb T_J	Thermal Resistance Junction-ambient Maximum Lead Temperature For Soldering Purpose	Max	62.5 300	°C/W °C

ELECTRICAL CHARACTERISTICS ($T_{case} = 25$ °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0$	100			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating } T_C = 125^\circ\text{C}$			1 10	μA μA
I_{GSS}	Gate-body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 20 V$			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250 \mu A$	2	3	4	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS} = 10 V$ $I_D = 7 A$		0.115	0.13	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g_{fs} (*)	Forward Transconductance	$V_{DS} = 15 V$ $I_D = 7 A$		20		S
C_{iss} C_{oss} C_{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V, f = 1 MHz, V_{GS} = 0$		460 70 30		pF pF pF

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ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on Delay Time Rise Time	$V_{DD} = 50 \text{ V}$ $I_D = 7 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$ (Resistive Load, Figure 3)		16 25		ns ns
Q_g Q_{gs} Q_{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 80 \text{ V}$ $I_D = 12 \text{ A}$ $V_{GS} = 10 \text{ V}$		15.5 3.7 4.7	21	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$ t_f	Turn-off Delay Time Fall Time	$V_{DD} = 50 \text{ V}$ $I_D = 7 \text{ A}$ $R_G = 4.7 \Omega$, $V_{GS} = 10 \text{ V}$ (Resistive Load, Figure 3)		32 8		ns ns

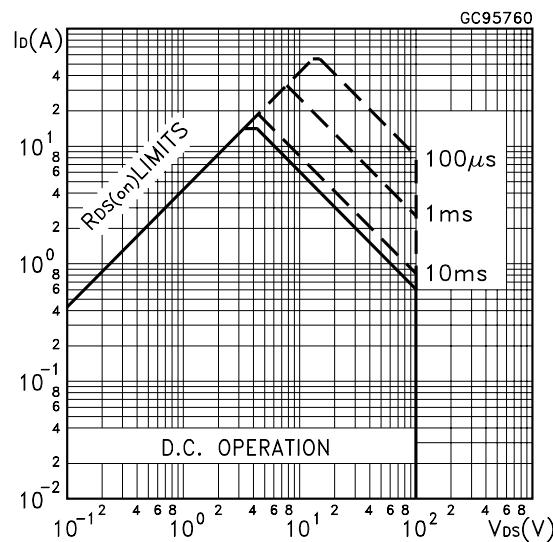
SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM} (\bullet)$	Source-drain Current Source-drain Current (pulsed)				15 60	A A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 14 \text{ A}$ $V_{GS} = 0$			1.5	V
t_{rr} Q_{rr} I_{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 14 \text{ A}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 50 \text{ V}$ $T_j = 150^\circ\text{C}$ (see test circuit, Figure 5)		90 230 5		ns nC A

(*)Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

(•)Pulse width limited by safe operating area.

Safe Operating Area for TO-220



Safe Operating Area for TO-220FP

